Supertex inc.



P-Channel Enhancement Mode **Vertical DMOS FETs**

Features

- High input impedance and high gain
- Low power drive requirement
- Ease of paralleling ►
- Low C_{ISS} and fast switching speeds
- Excellent thermal stability
- Integral source-drain diode
- Free from secondary breakdown

Applications

- Logic level interfaces ideal for TTL and CMOS
- Solid state relays
- Analog switches
- Power management
- **Telecom switches**

General Description

This low threshold enhancement-mode (normally-off) transistor utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures. this device is free from thermal runaway and thermallyinduced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

| Davis | Package O | ptions | BV _{DSS} /BV _{DGS} | R _{DS(ON)} | | | |
|--------|-------------------|------------|--------------------------------------|---------------------|--------------|--|--|
| Device | TO-236AB (SOT-23) | TO-92 | (V) | (max) (Ω) | (max) (V) | | |
| TP2104 | TP2104K1-G | TP2104N3-G | -40 | 6.0 | -2.0 | | |

Value

BV_{DSS}

 $\mathsf{BV}_{\mathsf{DGS}}$

±20V

+300°C

-55°C to +150°C

compliant ('Green')

Absolute Maximum Ratings



Drain-to-source voltage

Gate-to-source voltage

Soldering temperature*

referenced to device ground.

Drain-to-gate voltage

Parameter

Pin Configuration



Distance of 1.6mm from case for 10 seconds.

Operating and storage temperature

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation

of the device at the absolute rating level may affect device reliability. All voltages are

Package may or may not include the following marks: Si or TO-236AB (SOT-23) (K1)

Thermal Characteristics

| Package | I _D (continuous) [†] (mA) | I _D (pulsed) (A) | Power Dissipation @ T _A = 25°C (W) | <i>θ_{jc}</i> ∘C/W | θ _{ja} °C/W | l _{DR} † (mA) | l _{DRM} (A) |
|-------------------|---|-----------------------------------|---|-------------------------------|-------------------------|---------------------------|-------------------------|
| TO-236AB (SOT-23) | -160 | -0.8 | 0.36 | 200 | 350 | -160 | -0.8 |
| TO-92 | -250 | -1.0 | 0.74 | 125 | 170 | -250 | -1.0 |

† I_{D} (continuous) is limited by max rated T_{i} .

Electrical Characteristics (*T_A* = 25°C unless otherwise specified)

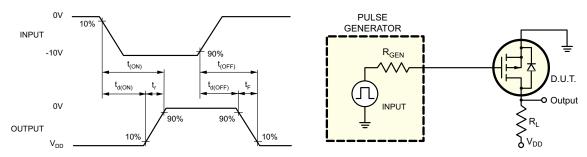
| Sym | Parameter | Min | Тур | Мах | Units | Conditions | | |
|---------------------|--|------|------|------|-------|--|--|--|
| BV _{DSS} | Drain-to-source breakdown voltage | -40 | - | - | V | V _{GS} = 0V, I _D = -1.0mA | | |
| $V_{GS(th)}$ | Gate threshold voltage | -1.0 | - | -2.0 | V | $V_{gs} = V_{Ds}, I_{D} = -1.0 \text{mA}$ | | |
| $\Delta V_{GS(th)}$ | Change in $V_{_{GS(th)}}$ with temperature | - | 5.8 | 6.5 | mV/ºC | $V_{GS} = V_{DS}, I_{D} = -1.0 \text{mA}$ | | |
| I _{GSS} | Gate body leakage | - | -1.0 | -100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | | |
| | | | - | -10 | μA | V_{GS} = 0V, V_{DS} = Max Rating | | |
| I _{DSS} | Zero gate voltage drain current | - | - | -1.0 | mA | V_{DS} = 0.8 Max Rating, V_{GS} = 0V, T_{A} = 125°C | | |
| I _{D(ON)} | On-state drain current | -0.6 | - | - | А | V _{GS} = -10V, V _{DS} = -25V | | |
| | Static drain-to-source on-state | - | - | 10 | Ω | V _{GS} = -4.5V, I _D = -50mA | | |
| R _{DS(ON)} | resistance | | - | 6.0 | | V _{GS} = -10V, I _D = -500mA | | |
| $\Delta R_{DS(ON)}$ | Change in $R_{DS(ON)}$ with temperature | - | 0.55 | 1.0 | %/°C | V _{GS} = -10V, I _D = -500mA | | |
| G _{FS} | Forward transconductance | 150 | 200 | - | mmho | V _{DS} = -25V, I _D = -500mA | | |
| C _{ISS} | Input capacitance | - | 35 | 60 | | V _{GS} = 0V, | | |
| C _{oss} | Common source output capacitance | - | 22 | 30 | pF | $V_{\rm DS} = -25V,$ | | |
| C _{RSS} | Reverse transfer capacitance | - | 8.0 | 10 | | f = 1.0 MHz | | |
| t _{d(ON)} | Turn-on delay time | - | 4.0 | 6.0 | | | | |
| t, | Rise time | - | 4.0 | 8.0 | 20 | $V_{DD} = -25V,$ | | |
| t _{d(OFF)} | Turn-off delay time | | 5.0 | 9.0 | ns | $I_{D} = -500 \text{mA},$ $R_{GEN} = 25\Omega$ | | |
| t _r | Fall time | - | 5.0 | 8.0 | | GEN | | |
| V _{SD} | Diode forward voltage drop | - | -1.2 | -2.0 | V | V _{GS} = 0V, I _{SD} = -500mA | | |
| t | Reverse recovery time | _ | 400 | - | ns | $V_{gs} = 0V, I_{sp} = -500mA$ | | |

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)

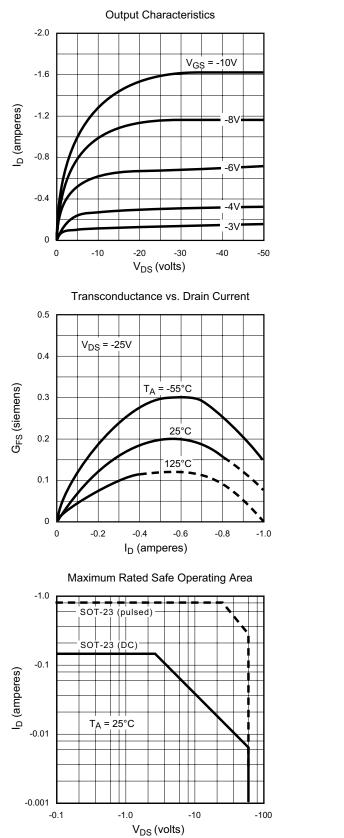
2. All A.C. parameters sample tested.

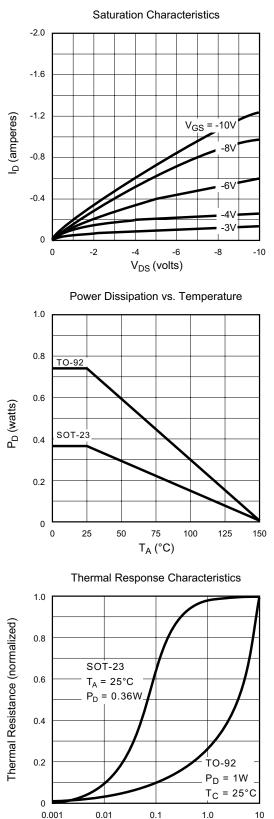
Switching Waveforms and Test Circuit



TP2104

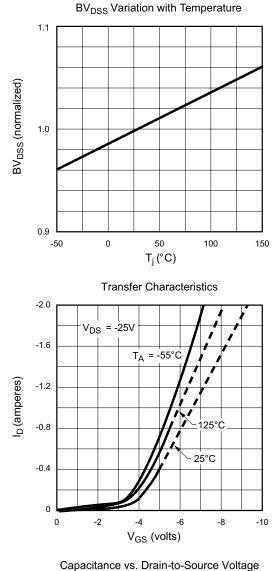
Typical Performance Curves



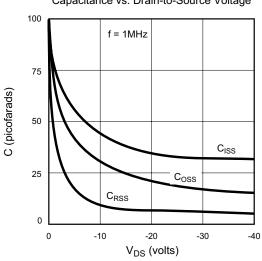


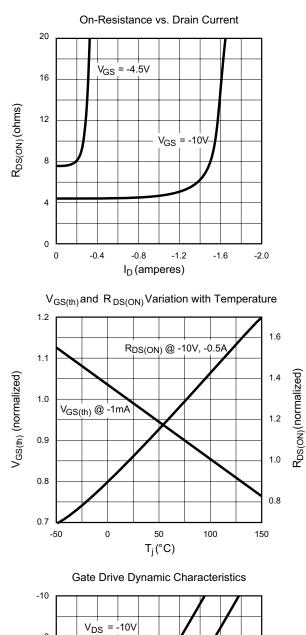
t_p (seconds)

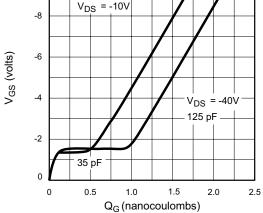
TP2104



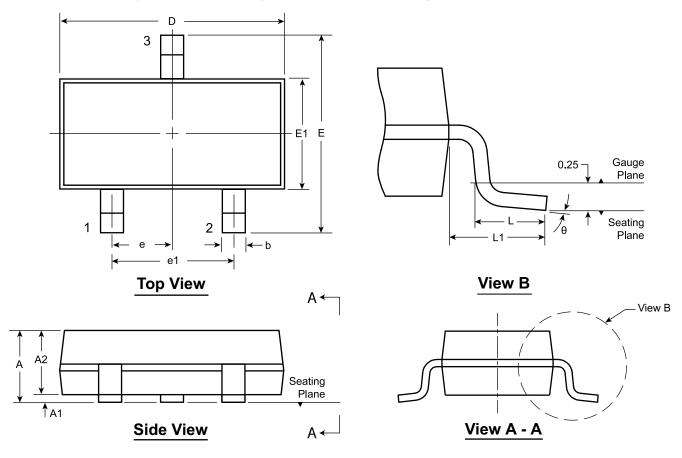
Typical Performance Curves (cont.)







3-Lead TO-236AB (SOT-23) Package Outline (K1) 2.90x1.30mm body, 1.12mm height (max), 1.90mm pitch



| Symb | ol | Α | A1 | A2 | b | D | E | E1 | е | e1 | L | L1 | θ | | |
|-------------------|-----|------|------|------|------|------|------|------|------|----------------------|------|-------------|---|------------|------------|
| Dimension (mm) | MIN | 0.89 | 0.01 | 0.88 | 0.30 | 2.80 | 2.10 | 1.20 | 0.05 | 0.95 1.90 BSC BSC | 0 50 | | | | 0 0 |
| | NOM | - | - | 0.95 | - | 2.90 | - | 1.30 | | | | 0.54 REF | - | | |
| | MAX | 1.12 | 0.10 | 1.02 | 0.50 | 3.04 | 2.64 | 1.40 | | | | 0.60 | | 8 0 | |

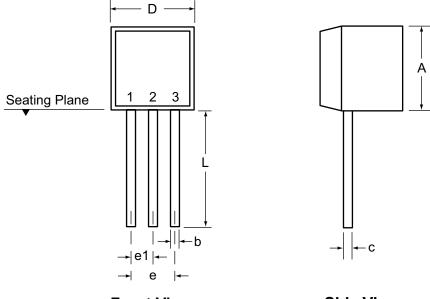
JEDEC Registration TO-236, Variation AB, Issue H, Jan. 1999.

† This dimension is a non-JEDEC dimension.

Drawings not to scale.

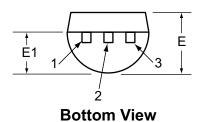
Supertex Doc.#: DSPD-3TO236ABK1, Version B072208.

3-Lead TO-92 Package Outline (N3)



Front View

Side View



| Symbol | | Α | b | С | D | E | E1 | е | e1 | L |
|------------------------|-----|------|-------|-------|------|------|------|------|------|-------|
| Dimensions (inches) | MIN | .170 | .014† | .014† | .175 | .125 | .080 | .095 | .045 | .500 |
| | NOM | - | - | - | - | - | - | - | - | - |
| | MAX | .210 | .022† | .022† | .205 | .165 | .105 | .105 | .055 | .610* |

JEDEC Registration TO-92.

* This dimension is not specified in the original JEDEC drawing. The value listed is for reference only.

† This dimension is a non-JEDEC dimension.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO92N3, Version D080408.

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